S22 9	72	S224 with (via throughole through adj hole through-hole chip near through throughchip) with (back backside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 14:34
S23 5	1837	backgrind$4 back-grind$4 back adj grind$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 14:34
S23 6	16	S235 with (trench plug) with (back backside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 14:36
S23 7	18	S235 with (trench plug) with (back backside underside bottomside (bottom lower under) adj (side surface))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 14:36
S23 8	18	S235 with (trench plug) with (back backside underside bottomside (bottom lower under) adj (side surface))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 14:37
S23 3	96	S232 and (@ad < "19990601") and (paste powder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 14:37
S23 4	2128	(trench plug) with (expos$6) with (back backside underside under adj side bottom adj side bottomside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 14:37
S23 9	2891	(trench plug) with (expos$6) with (back backside underside bottomside (bottom lower under) adj (side surface))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 14:37
S24 0	39	(S238 S239) and (@ad < "19990601") and (paste powder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 14:38
S19 8	3726	((438/637) or (438/640) or (438/675) or (438/977) or (438/928)).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/12/12 15:52
L1	4157	((438/637) or (438/640) or (438/675) or (438/977) or (438/928)).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/12/12 15:52

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S225	72	S224 with (via throughole through adj hole through-hole chip near through throughchip) with (back backside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/14 19:15
S220	68	S219 with (via throughole through adj hole through-hole chip near through throughchip) with (back backside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/14 19:15
S224	1835	backgrind$4 back-grind$4 back adj grind$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/14 19:15
S227	0	S226 and (@ad < "19980601") and (paste powder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/14 19:16
S226	72	S224 with (via throughole through adj hole through-hole chip near through throughchip) with (back backside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/14 19:16
S221	0	S220 and (@ad < "19980601") and (paste powder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/14 19:16
S231	2110	(via viahole throughole through adj hole through-hole chip near through throughchip) with (expos$6) with (back backside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/14 19:28
S230	134834	(via viahole throughole through adj hole through-hole chip near through throughchip) with (back backside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/14 19:28
S228	0	S226 and (@ad < "19990601") and (paste powder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/14 19:29
S232	2411	(via viahole throughole through adj hole through-hole chip near through throughchip) with (expos$6) with (back backside underside under adj side bottom adj side bottomside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/15 14:33